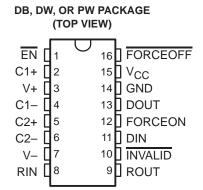
- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operate With 3-V to 5.5-V V_{CC} Supply
- Designed to Operate up to 512 kbit/s
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . $4 \times 0.1 \mu F$
- Accept 5-V Logic Input With 3.3-V Supply
- Designed to be Interchangeable With Maxim MAX3221C and MAX3221E
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15-kV Using Human Body Model (HBM)
- **Applications**
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and **Hand-Held Equipment**
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) **Packages**



description

The MAX3221 devices consist of one line driver, one line receiver, and a dual charge-pump circuit with ± 15 -kV ESD protection pin-to-pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector, and meet the requirements of TIA/EIA-232-F. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. These devices are designed to operate at data signaling rates up to 512 kbit/s, and a maximum of 30-V/µs driver output slew rate.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the devices do not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and $\overline{\text{EN}}$ is high, both drivers and receivers are shut off, and the supply current is reduced to 1 μ A. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the devices are activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 µs. INVALID is low (invalid data) if the receiver input voltage is between -0.3 V and 0.3 V for more than 30 µs. Refer to Figure 4 for receiver input levels.

The MAX3221C is characterized for operation over the temperature range of 0°C to 70°C. The MAX3221I is characterized for operation over the temperature range of -40°C to -85°C.



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Function Tables

EACH DRIVER

		INPUTS	OUTPUT		
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered-off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

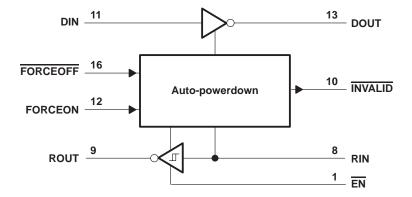
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

	INPUTS					
RIN	EN	VALID RIN RS-232 LEVEL	ROUT			
L	L	Х	Н			
Н	L	Х	L			
Х	Н	X	Z			
Open	L	No	Н			

H = high level, L = low level, X = irrelevant, Z = high impedance (off),

logic diagram (positive logic)



Open = disconnected input or connected driver off

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage, V+ (see Note 1)	
Negative output supply voltage, V– (see Note 1)	0.3 V to -7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON, EN)	
Receiver	25 V to 25 V
Output voltage range, VO: Driver	13.2 V to 13.2 V
Receiver (INVALID)	\dots -0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Note 2): DB package	131°C/W
DW package	105°C/W
PW package	149°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3 and Figure 5)

			MIN	NOM	MAX	UNIT
Supply voltage	V _{CC} = 3.3 V		3	3.3	3.6	V
Supply voltage	V _{CC} = 5 V		4.5	5	5.5	V
Driver and central high level input valtage. Vv.	DIN, FORCEOFF, FORCEON, EN	V _{CC} = 3.3 V	2			V
Driver and control high-level input voltage, VIH		V _{CC} = 5 V	2.4			٧
Driver and control low-level input voltage, VIL	DIN, FORCEOFF, FORCEON, EN				0.8	V
Receiver input voltage, V _I			-25		25	V
Operating free-air temperature, Тд	MAX3221C		0		70	°C
Operating nee-all temperature, 14	MAX3221I		-40		85	C

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

	PARAM	ETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
П	Input leakage current	FORCEOFF, FORCEON, EN			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
loc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
ICC Supply current	Cappi, Callon	Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

 $[\]ddagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

	PARAMETER	TEST C	CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	DOUT at R _L = $3 \text{ k}\Omega$ to GND,	DIN = GND	5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GND,	DIN = V _{CC}	-5	-5.4		V
lН	High-level input current	$V_I = V_{CC}$			±0.01	±1	μΑ
Iμ	Low-level input current	V _I at GND			±0.01	±1	μΑ
	Short-circuit	V _{CC} = 3.6 V,	VO = 0 V		±25	±60	mA
ios	OS output current‡	$V_{CC} = 5.5 V,$	V _O = 0 V]	±35 ±		IIIA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V	300	10M		Ω
l _{off}	Output leakage current	FORCEOFF = GND,	$V_O = \pm 12 \text{ V}, V_{CC} = 0 \text{ to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

	PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, See Figure 1	$R_L = 3 \text{ k}\Omega,$	512			kbit/s
tsk(p)	Pulse skew§	C _L = 150 pF to 2500 pF,	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	V/us
JK(II)	(see Figure 1)	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$	C _L = 150 pF to 2500 pF	4		30	ν/μ5

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V $_{CC}$ = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V $_{CC}$ = 5 V \pm 0.5 V.



[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tplH - tpHL|.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/	Positive-going input threshold voltage	V _{CC} = 3.3 V		1.6	2.4	V
VIT+	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	V
\/	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
VIT-	Negative-going input theshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} –)			0.5		V
loff	Output leakage current	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_{I} = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C. NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

	PARAMETER	TEST CONDITIONS	MIN TYP†	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C _I = 150 pF, See Figure 2	150		ns
tPHL	Propagation delay time, high- to low-level output	CL = 130 pr , See rigure 2	150		ns
t _{en}	Output enable time	$C_1 = 150 \text{ pF}, R_1 = 3 \text{ k}\Omega, \text{ See Figure 3}$	200		ns
tdis	Output disable time	CL = 150 pr, KL = 5 ksz, See Figure 5	200		ns
tsk(p)	Pulse skew [‡]	See Figure 2	50		ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

‡ Pulse skew is defined as $|t_{PLH} - t_{PHL}|$. NOTE 3. Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
VT+(VALID)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
VT-(VALID)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(INVALID)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
VOH	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}	V _{CC} - 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}			0.4	٧

 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V and T_A = 25°C.

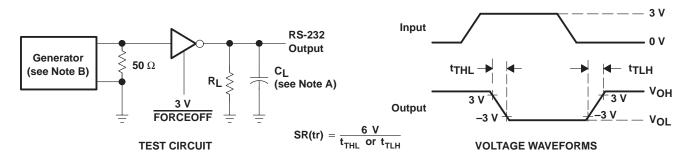
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 4)

	PARAMETER		UNIT
tVALID	Propagation delay time, low- to high-level output	1	μs
^t INVALID	Propagation delay time, high- to low-level output	30	μs
t _{en}	Receiver and driver output enable time	100	μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

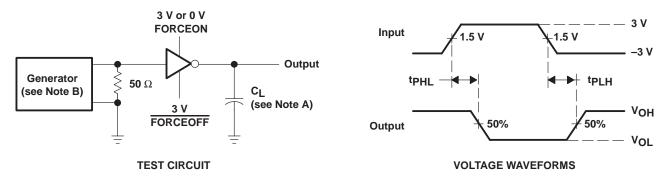


PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: $Z_O = 50~\Omega$, 50% duty cycle, $t_\Gamma \le 10~ns$, $t_f \le 10~ns$.

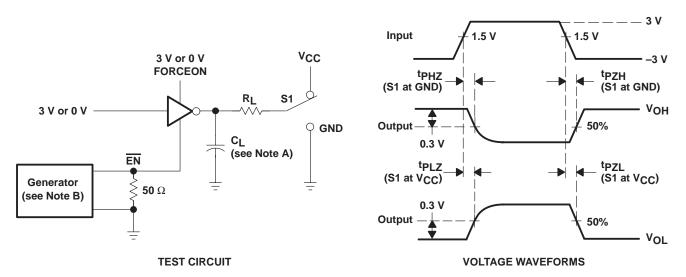
Figure 1. Driver Slew Rate



- NOTES: A. C_I includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR = 512 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 2. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



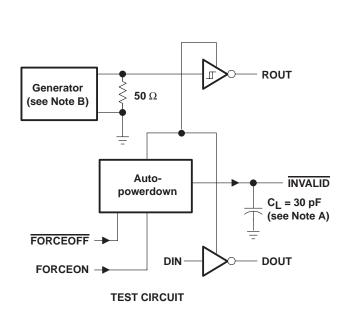
NOTES: A. C_L includes probe and jig capacitance.

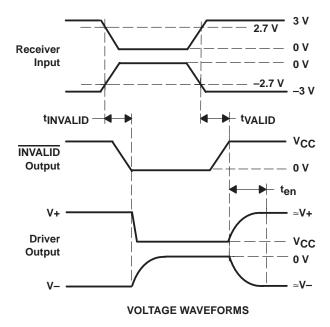
- B. The pulse generator has the following characteristics: PRR = 512 kbit/s, $Z_O = 50~\Omega$, 50% duty cycle, $t_\Gamma \le 10~ns$, $t_f \le 10~ns$.
- C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- D. tpzL and tpzH are the same as ten.

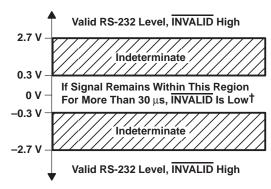
Figure 3. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION







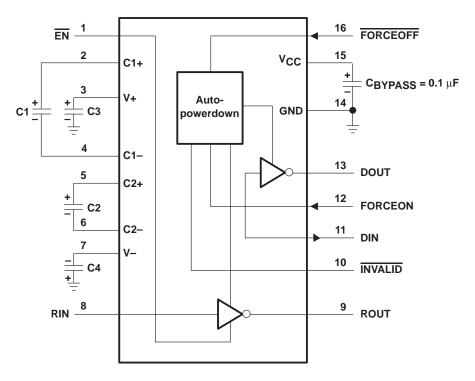
 † Auto-powerdown disables drivers and reduces supply current to 1 $\mu A.$

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 512 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns.

Figure 4. INVALID Propagation Delay Times and Driver Enabling Time

APPLICATION INFORMATION



V_{CC} vs CAPACITOR VALUES

Vcc	C1	C2, C3, and C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 5. Typical Operating Circuit and Capacitor Values

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